

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn-Currently Amended) A method of forming a patterned film made of a conductive material including a linear portion by frame plating, the method comprising:  
forming a frame having an undercut near a bottom thereof on a base layer; and  
forming the patterned film by plating through the use of the frame such that the linear portion has a first portion and a second portion, wherein the second portion is closer to the base layer than the first portion, and wherein the second portion touches the base layer and has a width greater than a width of the first portion.
2. (Withdrawn) The method according to claim 1, wherein the patterned film is formed to include a plurality of linear portions disposed side by side.
3. (Currently Amended) A patterned film made of a conductive material, the patterned film being disposed on a base layer and including a linear portion, wherein the linear portion has a first portion and a second portion, wherein the second portion is closer to the base layer than the first portion, and wherein the second portion touches the base layer, the second portion having a width greater than a width of the first portion.
4. (Previously Presented) The patterned film according to claim 3, including a plurality of linear portions disposed side by side.